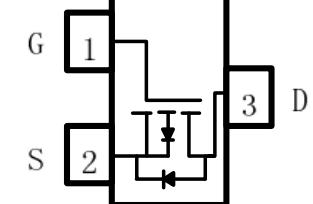
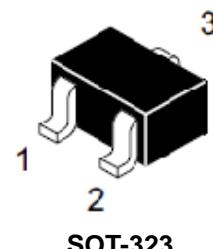


## **WPM1488**

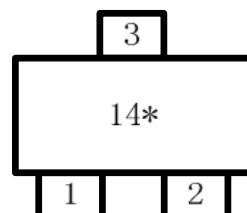
**Single P-Channel, -12V, -1.4A, Power MOSFET**

[www.sh-willsemi.com](http://www.sh-willsemi.com)

<b>V<sub>DS</sub> (V)</b>	<b>Typical R<sub>ds(on)</sub> (Ω)</b>	<b>I<sub>D</sub> (A)</b>
<b>-12</b>	0.080@ V <sub>GS</sub> = - 4.5V	-1.2
	0.086@ V <sub>GS</sub> = - 3.6V	-1.0
	0.105@ V <sub>GS</sub> = - 2.5V	-1.0



**Pin configuration (Top view)**



14 = Specific Device Code

\* = Date Code

### **Marking**

### **Order information**

<b>Device</b>	<b>Package</b>	<b>Shipping</b>
WPM1488-3/TR	SOT-323	3000/Reel&Tape

## **Applications**

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

### Absolute Maximum ratings

Parameter	Symbol	10 S	Steady State	Unit
Drain-Source Voltage	V <sub>DS</sub>	-12	V	
Gate-Source Voltage	V <sub>GS</sub>	±8		
Continuous Drain Current <sup>a d</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-1.5	A
	T <sub>A</sub> =70°C		-1.2	
Maximum Power Dissipation <sup>a d</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.44	W
	T <sub>A</sub> =70°C		0.28	
Continuous Drain Current <sup>b d</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-1.4	A
	T <sub>A</sub> =70°C		-1.1	
Maximum Power Dissipation <sup>b d</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.39	W
	T <sub>A</sub> =70°C		0.25	
Pulsed Drain Current <sup>c</sup>	I <sub>DM</sub>	-10		A
Operating Junction Temperature	T <sub>J</sub>	-55 to 150		°C
Lead Temperature	T <sub>L</sub>	260		°C
Storage Temperature Range	T <sub>stg</sub>	-55 to 150		°C

### Thermal resistance ratings

Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	t = 10 s	R <sub>JA</sub>	284	335
	Steady State		321	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	t = 10 s	R <sub>JA</sub>	315	338
	Steady State		358	
Junction-to-Case Thermal Resistance	R <sub>JC</sub>	110	165	

a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper

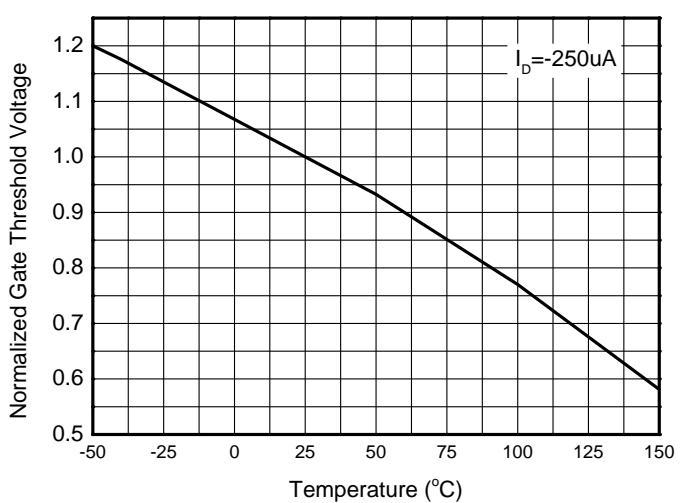
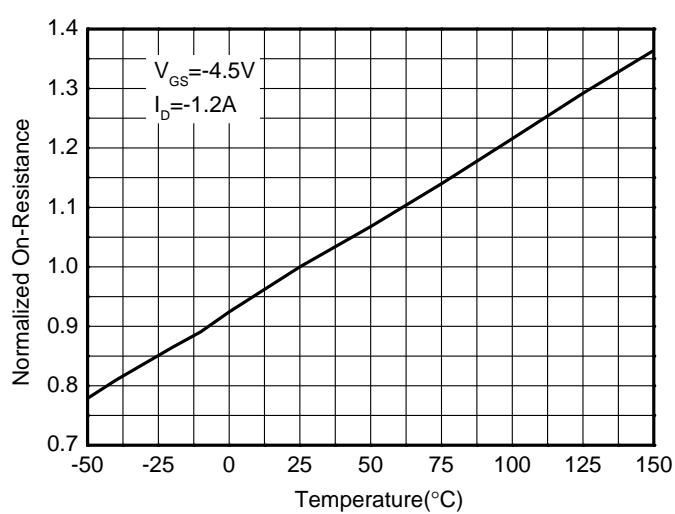
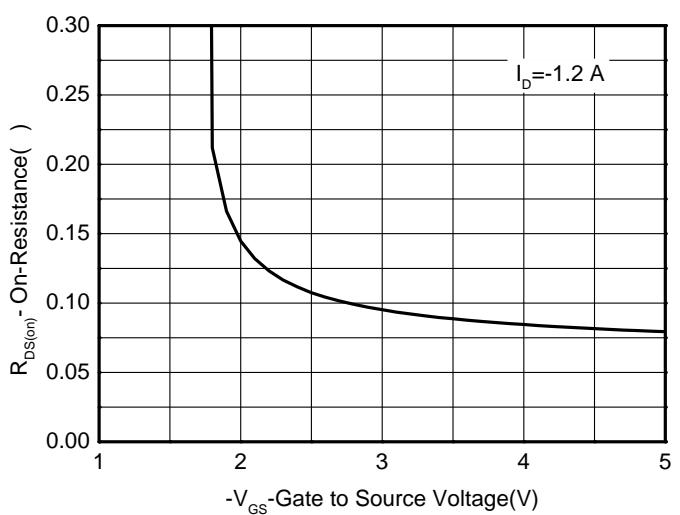
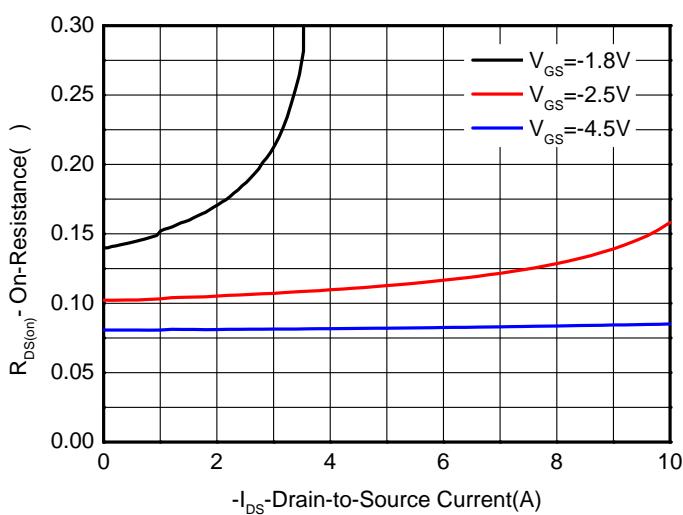
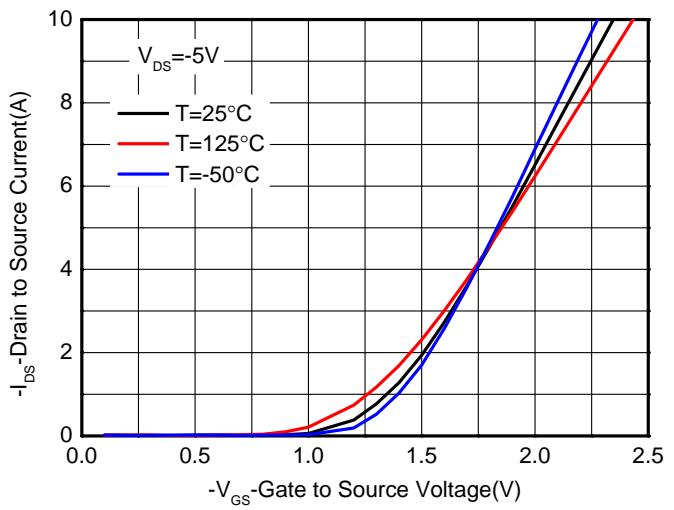
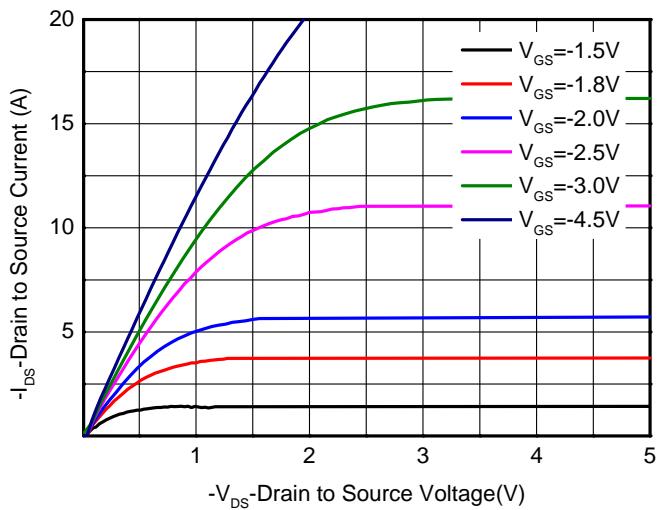
b Surface mounted on FR-4 board using minimum pad size, 1oz copper

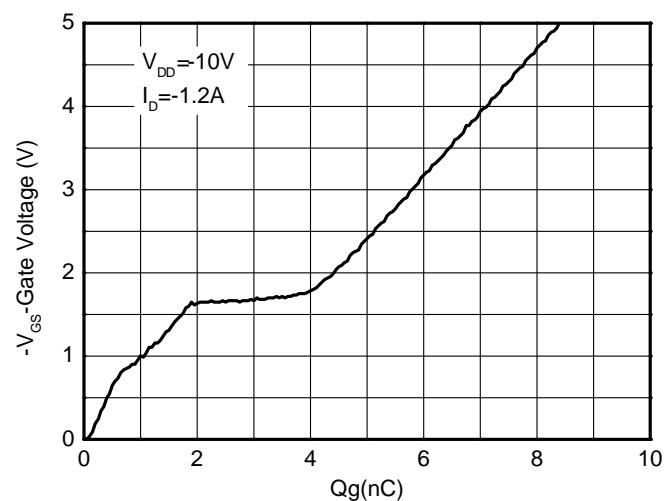
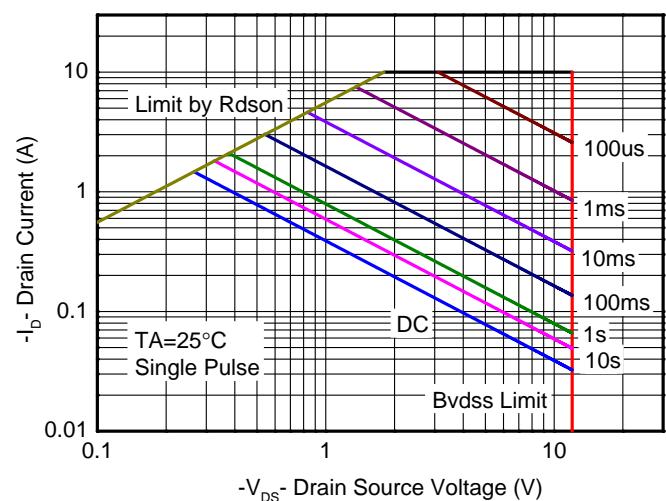
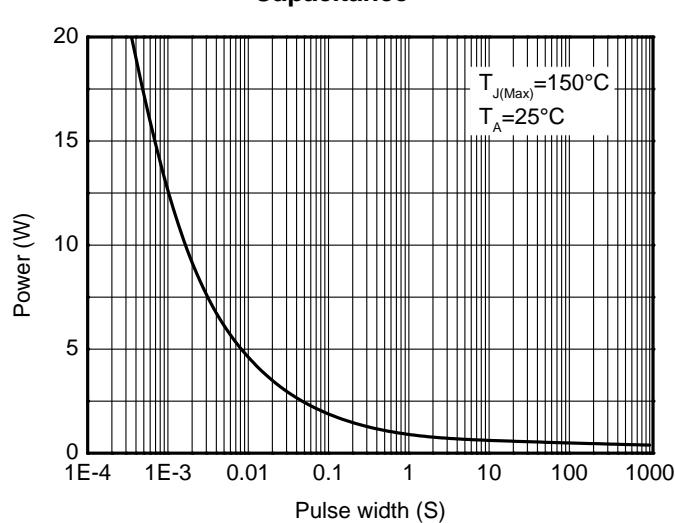
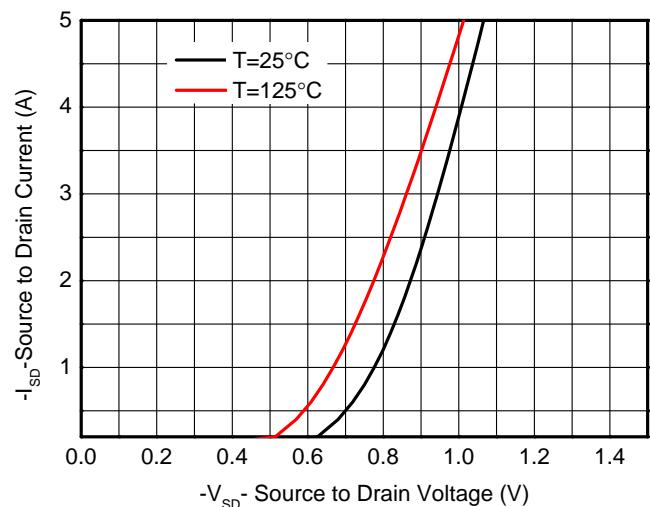
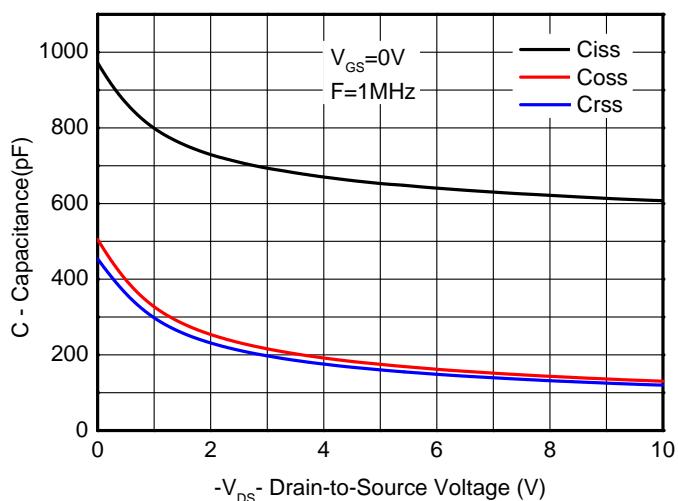
c Pulse width<380μs, Duty Cycle<2%

d Maximum junction temperature T<sub>J</sub>=150°C.

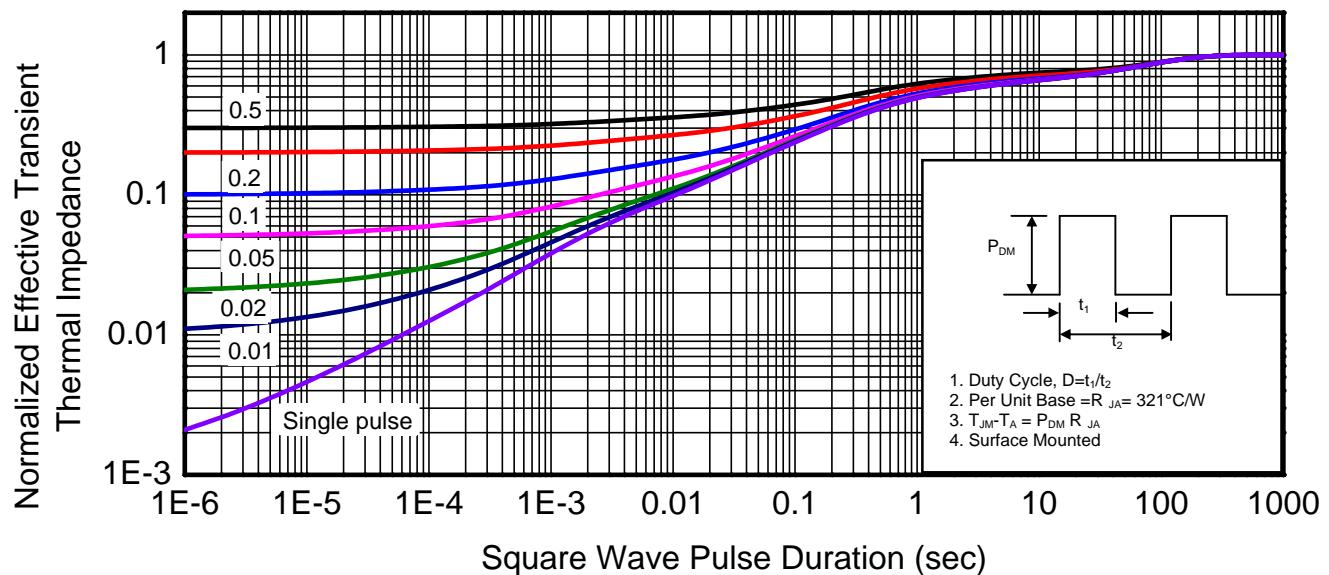
**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

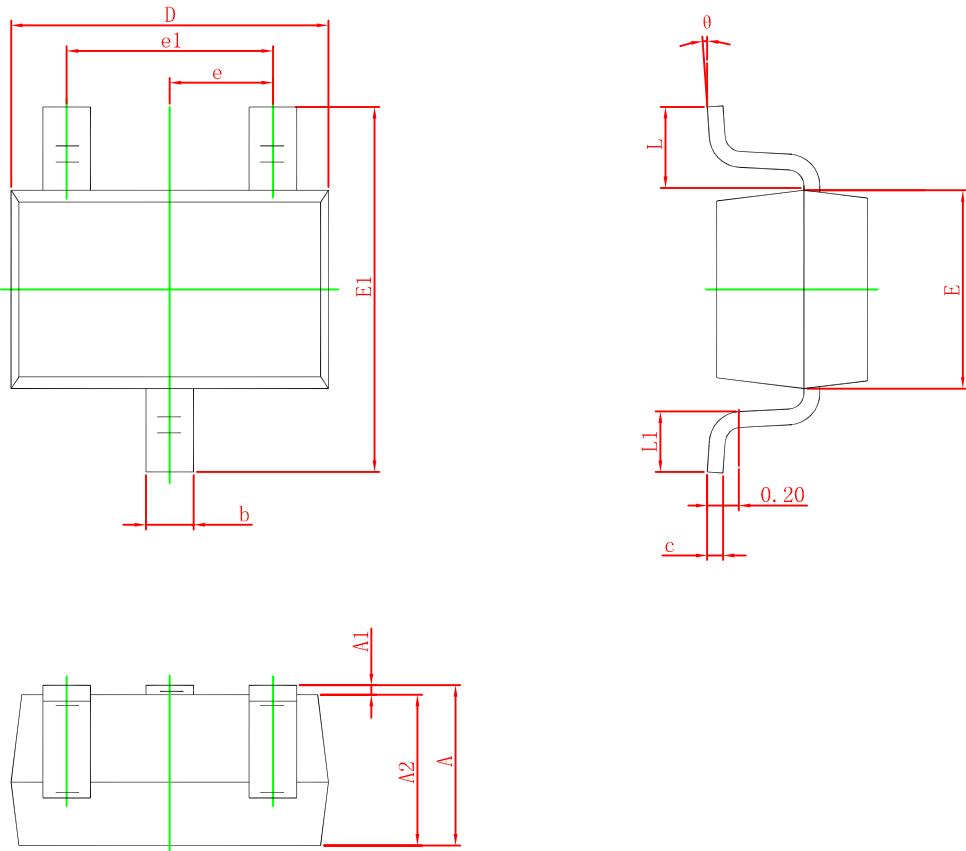
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0 \text{ V}, I_D = -250\mu\text{A}$	-12			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}$			-1	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8\text{V}$			$\pm 1$	$\mu\text{A}$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-0.45	-0.65	-0.85	V
Drain-to-source On-resistance <sup>b, c</sup>	$R_{DS(\text{on})}$	$V_{GS} = -4.5\text{V}, I_D = -1.2\text{A}$		80	120	$\text{m}\Omega$
		$V_{GS} = -3.6\text{V}, I_D = -1.0\text{A}$		86	140	
		$V_{GS} = -2.5\text{V}, I_D = -1.0\text{A}$		105	160	
Forward Transconductance	$g_{FS}$	$V_{DS}=-5\text{V}, I_D=-1.2\text{A}$		9		S
<b>CAPACITANCES, CHARGES</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz},$ $V_{DD} = -10 \text{ V}$		607		$\text{pF}$
Output Capacitance	$C_{OSS}$			130		
Reverse Transfer Capacitance	$C_{RSS}$			120		
Total Gate Charge	$Q_{G(\text{TOT})}$	$V_{GS} = -4.5 \text{ V},$ $V_{DD} = -10 \text{ V},$ $I_D = -1.2\text{A}$		7.85		$\text{nC}$
Threshold Gate Charge	$Q_{G(\text{TH})}$			0.85		
Gate-to-Source Charge	$Q_{GS}$			1.9		
Gate-to-Drain Charge	$Q_{GD}$			2.1		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$td(\text{on})$	$V_{GS} = -4.5 \text{ V},$ $V_{DD} = -10\text{V},$ $I_D=-1.2\text{A},$ $R_G=6 \Omega$		30		$\text{ns}$
Rise Time	$tr$			32		
Turn-Off Delay Time	$td(\text{off})$			62		
Fall Time	$tf$			18		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	$V_{SD}$	$V_{GS} = 0 \text{ V}, I_S = -1.0\text{A}$		-0.8	-1.5	V

**Typical Characteristics (Ta=25°C, unless otherwise noted)**




Gate charge Characteristics

**Transient thermal response (Junction-to-Ambient)**


**Package outline dimensions**
**SOT-323**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP.		0.026 TYP.	
e1	1.200	1.400	0.047	0.055
L	0.525 REF.		0.021 REF.	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

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[BSS340NWH6327XTSA1](#) [MCM3400A-TP](#) [DMTH10H4M6SPS-13](#) [IPS60R1K0PFD7SAKMA1](#) [IPS60R360PFD7SAKMA1](#)  
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